

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-------------------|---|-----------------|----------|
| Applicant: | Chuen Rong Leu et al. | | |
| Assignee: | Bridge Semiconductor Corporation | | |
| Title: | METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR | | |
| Serial No.: | Unknown | Filed: | Herewith |
| Examiner: | Unknown | Group Art Unit: | Unknown |
| Atty. Docket No.: | BDG024-1 | | |

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

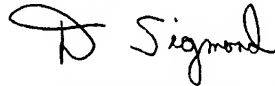
Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98, Applicant hereby provides the enclosed Form PTO-1449.

Copies of the documents on the attached Form PTO-1449 are not enclosed because they were previously submitted to or cited by the U.S. Patent Office in U.S. Application Serial No. 10/714,794 filed November 17, 2003, U.S. Application Serial No. 10/235,331 filed September 5, 2002, U.S. Application Serial No. 09/939,140 filed June 11, 2001, U.S. Application Serial No. 09/878,626 filed June 11, 2001 and/or U.S. Application Serial No. 09/687,619 filed October 13, 2000.

The above-identified application is a continuation of the '794 application, which is a continuation-in-part of the '331 application, which is a divisional of the '140 application, which is a continuation-in-part of the '626 application, which is a continuation-in-part of the '619 application. Therefore, the documents need not be resubmitted in order to be considered by the Examiner. See M.P.E.P § 609.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "D. Sigmond". The signature is written in a cursive, flowing style.

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Attorney for Applicant
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(303) 554-8667 (fax)

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| Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office | | | | | Atty Docket No. BDG024-1 | | Serial No. | |
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| | AP | U.S. Application Serial No. 09/464,562, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Strips And Via-Fill" | | | | | | |
| | AQ | U.S. Application Serial No. 09/464,561, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Strips-In-Via And Plating" | | | | | | |
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| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
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| | AO | | | | | | | |
| Other Art (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | |
| | AP | | | | | | | |
| | AQ | | | | | | | |
| Examiner | | | Date Considered | | | | | |
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| Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office | | | | | Atty Docket No. BDG024-1 | | Serial No. | |
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| | | | | | Filing Date | | Group Art Unit | |
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| Foreign Patent Documents | | | | | | | | |
| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
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| U.S. Patent Documents | | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate | |
| | AA | | | | | | | |
| Foreign Patent Documents | | | | | | | | |
| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
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| Examiner | | | Date Considered | | | | | |
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| | AA | | | | | | |
| Foreign Patent Documents | | | | | | | |
| | | | | | | | Translation |
| | | Document | Date | Country | Class | Subclass | Yes No |
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| | | | | | Filing Date | | Group Art Unit | |
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| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
| | AN | | | | | | | |
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